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04-22-2002



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original documents or copy thereof.

1. Name of conveying party(ies):

Nippon Pillar Packing Co., Ltd.

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date: March 31, 2002

2. Name and address of receiving party(ies)

Name: Nissin Electric Co., Ltd.

Internal Address:

Street Address: 47, Umezu-Takase-cho,

Ukyo-ku, Kyoto-shi, Kyoto, Japan

City: State: ZIP:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/147,694 09/771,556  
09/497,799 09/805,778  
09/634,599

B. Patent No.(s)

6,053,973 6,187,279 6,153,166  
6,143,267 6,203,772  
6,153,165 6,217,842

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Felix J. D'Ambrosio

Internal Address: P.O. Box 2266 Eads Station  
Arlington, VA 22202

Street Address: 2001 Jefferson Davis Hwy.

Suite 1002

City: Arlington State: VA ZIP: 22202

6. Total number of applications and patents involved:

12

7. Total fee (37 CFR 3.41).....\$ 480.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Felix J. D'Ambrosio

Name of Person Signing

Signature

April 16, 2002

Date

Total number of pages including cover sheet, attachments, and document:

3

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments

PATENT  
REEL: 012795 FRAME: 0576

# ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) , and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, **Nippon Pillar Packing Co., Ltd.**, a corporation of **Japan**, located at **11-48, Nonakaminami 2-chome, Yodogawa-ku, Osaka-shi, Osaka, Japan**.

Hereby sell, assign and transfer to **Nissin Electric Co., Ltd.**, a corporation of **Japan** , having a place of business at **47, Umezu-Takase-cho, Ukyo-ku, Kyoto-shi, Kyoto, Japan**, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to the following patents and patent applications, and in any and all improvements which are disclosed in said patents and patent applications identified as follows:

<u>Patent No.</u>	<u>Issued on</u>	<u>Entitled</u>
6,053,973	April 25, 2000	Single Crystal SiC and A Method of Producing the Same
6,143,267	November 7, 2000	Single Crystal SiC and A Method of Producing the Same
6,153,165	November 28, 2000	Single Crystal SiC and Method of Producing the Same
6,187,279	February 13, 2001	Single Crystal SiC and Method of Producing the Same
6,203,772	March 20, 2001	Single Crystal SiC and A Method of Producing the Same
6,217,842	April 17, 2001	Single Crystal SiC and Method of Producing the Same
6,153,166	November 28, 2000	Single Crystal SiC and A Method of Producing the Same
<u>Patent Appln. No.</u>	<u>Filed on</u>	<u>Entitled</u>
09/147,694	July 1, 1998	SiC Complex and a Method of Producing the Same
09/497,799	February 4, 2000	Single Crystal SiC
09/634,599	August 8, 2000	Single Crystal SiC Composite Material for Producing a Semiconductor Device, and a Method of Producing the Same
09/771,556	January 30, 2001	Single Crystal SiC and a Method of Growing the Same
09/805,778	July 30, 1999	Material for Growing Single Crystal SiC and Method of Producing Single Crystal SiC

and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;


Agree that said Assignee may apply for and receive Letters Patent for said Patent Applications in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments,

powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Nippon Pillar Packing Co., Ltd.

March 31, 2002  
Date.....

By..........(L.S.)

Kiyohisa IWANAMI  
President